

Carbon erosion and deuterium retention of tungsten-doped amorphous carbon films exposure to deuterium plasma



P. Wang*, W. Jacob, P. A. Sauter, M. Balden

Motivation

- > Tritium retention in redeposited carbon is one of the most crucial issues in nuclear fusion
- > Use of carbon together with metallic plasma-facing materials will lead to cycles of erosion of the PFMs by hydrogen and subsequent deposition of mixed carbon-metal layers
- > Carbon-metal mixed layers will be subjected to further erosion
- > D retention in such film unknown

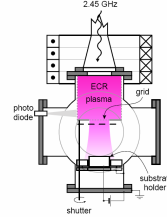
Experiments

Samples

- Preparation: Dual magnetron sputter deposition (Graphite: rf power, Tungsten: DC power)
- Film composition and thickness (a-C:W on silicon wafer, 0-7 at % W, Thickness: 300-1000 nm)

Deuterium plasma exposure

- ECR plasma ion source with freely expanding plasma beam (PlaQ)
- Ion energy: **30 eV/D, 100 eV/D**
- Ion flux: **$8.8 \times 10^{19} \text{ D/m}^2, 1.05 \times 10^{20} \text{ D/m}^2$**
- Fluence: from 1×10^{23} up to $7 \times 10^{25} \text{ D/m}^2$
- Sample temperature: **300 K**



Characterization

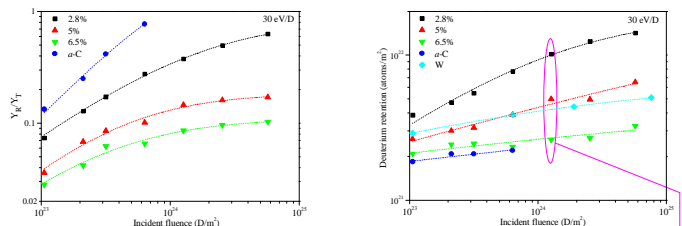
- Nuclear reaction analysis: Deuterium retention, 700 keV, $^3\text{He}^+$ beam
- Rutherford backscattering spectrometry: Composition and thickness changes, 4000 keV, $^4\text{He}^+$ beam
- Atomic force microscopy/X-ray photoelectron spectroscopy: Surface morphology and chemical bonding

Summary

Exposure of W-doped amorphous carbon films to deuterium plasma

- > Carbon removal rate of W-doped amorphous carbon films is clearly lower than the rate of pure amorphous carbon and decreases strongly with increasing W concentration. Carbon removal rates for a-C:W films decrease with increasing deuterium fluence due to a tungsten enriched-layer at the surface
- > D retention in a-C:W films increases monotonically with increasing fluence, no obvious saturation detected in the investigated region.
- > Deuterium penetrates surface tungsten-enriched layer and diffuses into the bulk a-C:W films, the diffusion depth is limited below to about 200 nm at 30 eV and increases to about 300 nm at 100 eV

Carbon erosion & deuterium retention

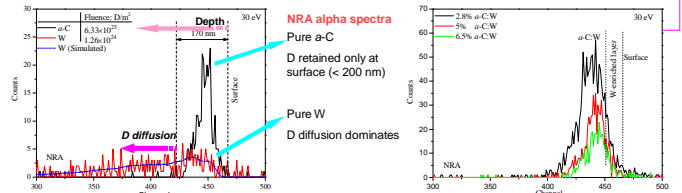


RBS analysis (Y_R : removed carbon amount, Y_T : total (initial) carbon amount)

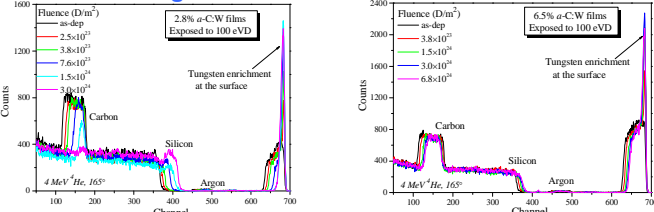
W-doping reduces erosion rate by factors from 2 to 7 depending on the W concentration, carbon removal tends to saturate after fluence of 10^{24} D/m^2 in 5% and 6.5% a-C:W films

NRA analysis

D retention in a-C:W films increases monotonically with increasing fluence, no obvious saturation detected. Deuterium penetrates surface tungsten-enriched layer and diffuses into the bulk, the diffusion depth is limited to about 200 nm

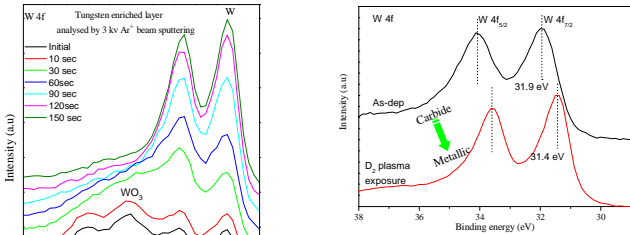


Surface: Tungsten enrichment



RBS analysis

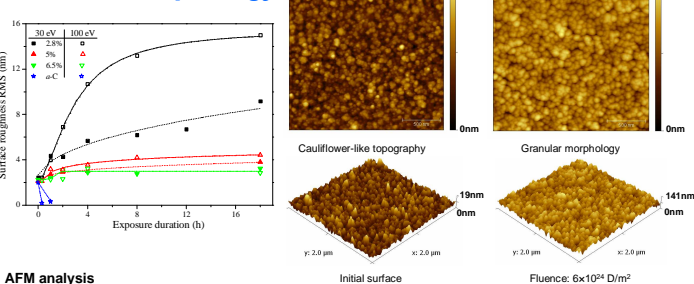
- W-rich layer develops at the surface – a result of preferential erosion of carbon
- W enrichment increases with fluence, no W sputtering at 30 eV
- W enrichment accompanied by a slight W sputtering due to D^+ ions at 100 eV



XPS analysis

- Tungsten carbide bonding in as-deposited film
- Tungsten metallic bonding after D plasma exposure

Surface: Morphology



AFM analysis

- Initial surface of a-C and a-C:W have comparable roughness
- Exposure of pure a-C film to deuterium plasma leads to an extremely smooth surface
- All tungsten-doped carbon films become even rougher after deuterium plasma exposure

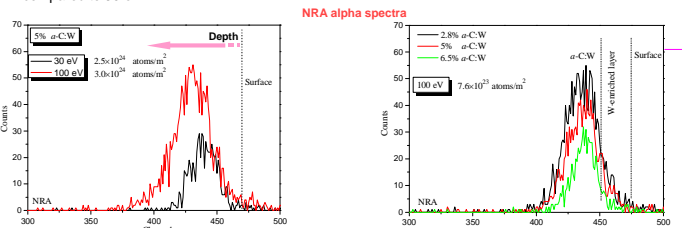
RBS analysis (Y_R : removed carbon/tungsten amount, Y_T : total carbon/tungsten amount)

W-doping reduces erosion rate by factors from 2 to 5 depending on the W concentration, no carbon removal saturation for all investigated films

A slight tungsten sputtering can be detected at 100 eV due to D^+ ions

NRA analysis

The diffusion depth reaches to 300 nm at 100 eV, and the deuterium retention is deeper and higher compared to 30 eV



*Corresponding author: Peng.Wang@ipp.mpg.de